

ISCAS 2024

Singapore | May 19-22, 2024

Resorts World Sentosa Convention Centre



Call for Special Sessions

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world's premiere forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS 2024 will be held in Singapore, from May 19 to 22, 2024. Special sessions complement the regular technical program by highlighting new and emerging research topics or innovative applications of established approaches. The topic of a special session proposal should be timely and compelling. While we welcome special sessions in all areas of Circuits and Systems, we are particularly interested in focused research topics, especially those with interdisciplinary and multidisciplinary nature, specifically those related to the conference innovation themes:

- *Emerging Technologies*
- *Big Data Processing*
- *Smart Systems for Automotive*
- *Artificial Intelligence*
- *Cognitive Computing and Deep Learning*
- *Personalized Healthcare Systems*
- *Sustainable Computing and Systems*
- *Brain: Innovation NeuroTechnologies*
- *Energy-aware Systems and Services*
- *5G and Multi-Gigabit*

Special sessions can also cover any other area focusing on challenging open problems of relevance in applications. The participation of speakers from the industry is encouraged and will be positively evaluated.

Special Sessions Proposals Submission Guidelines

Please submit proposals (approximately 3 pages) in pdf format by email to the Special Sessions Co-Chairs Mohamad Sawan (sawan@westlake.edu.cn), Volkan Kursun (volkan.kursun@bilkent.edu.tr), Nathalie Deltimple (nathalie.deltimple@ims-bordeaux.fr). All papers will be subject to the same peer review process as regular papers. The proposal should include the following information:

1. Title and Abstract

Propose a title and an abstract of no more than 200 words that will allow conference attendees to understand the topic and the focus.

2. Rationale

Please explain why the topic is novel, why it is relevant to the ISCAS community, and how it fits within the innovation themes listed above.

3. Proposed speakers

Provide a list of all talks and authors. Technical sessions are normally expected to have 5 papers. In exceptional cases (like industrial

talks, or contributions by particularly renowned speakers) it may be possible to have sessions of one talk without an associate paper or a talk which will have a double-time slot for the presentation.

4. Biographies

Provide a short bio of the session proposers. An essential aspect in evaluating special session proposals will be the timeliness of the topic, quality/track record of the proposers and speakers, coherence of the session, and expected value added to the overall technical program.

Important Dates:

Special Sessions Proposal:	Oct 1, 2023 (extended)
Special Sessions Proposal Notification:	Oct 7, 2023 (extended)
Special Session Papers Submission:	Oct 15, 2023
Authors' Decision Notification:	Jan 15, 2024



2024.ieee-iscas.org

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